

REMARKS

Favorable reconsideration of this application, in light of the following discussion and in view of the present amendments, is respectfully requested.

Claims 3 and 35-51 have been canceled. Claims 4-20, 22, 23, and 25-51 remain withdrawn, claim 2 is original and claims 1, 21, and 24 are amended by the present amendment. No new matter has been added by way of these amendments. New claims 52-55 are added herein. Exemplary support for the added claims can be found, for example, in Figs. 2-13G of the drawings. Therefore, claims 1, 2, 4-34 and 52-55 are pending in the present application.

I. Rejection Under 35 U.S.C. § 102(b)

Claims 1 and 2 were rejected under 35 U.S.C. § 102(b) as anticipated by U.S. Patent No. 6,228,467 to Taniguchi et al. ("Taniguchi"). This rejection is respectfully traversed.

Amended claim 1 recites a "multi-layer circuit wiring board comprising a laminate of films *and an adhesive layer for bonding said films*, each film having a wiring pattern formed on at least one surface thereof, wherein the wiring pattern formed on each film is electrically connected with the wiring pattern formed on another film which is disposed neighboring thereto through a via-contact layer formed in any one of the neighboring films, *each of said films having a thickness of 12.5 μm to 80 μm , and said adhesive layer having a thickness of 30 μm or less.*"

Taniguchi fails to disclose all of the features claimed in amended claim 1.

The Office asserts Taniguchi discloses a multi-layer circuit wiring board (no number) comprising a laminate of films 14/15/16 (film insulator, col. 3:24-27), each film having a wiring pattern 2 (electrical conductive pattern, col. 3:25) formed on at least one surface thereof, wherein the wiring pattern formed on each film is electrically connected with the wiring pattern formed on another film which is disposed neighboring thereto through a via-contact layer 3 (conductive paste filled in a through-hole, col. 3:6-8 and col. 3:25-26) formed in any one of the neighboring films.

However, Taniguchi fails to disclose an adhesive layer for bonding said films. Instead, Taniguchi discloses heat bonding of the films. Applicants respectfully direct the Office's attention to lines 62-67 of column 3 of Taniguchi which disclose "a base material (12) made of a film insulator having predetermined through-holes provided and an electrical conductive paste filled therein, is prepared, and the above-mentioned base materials (11) and (13) are heat-bonded with it interposed to form a multilayer structure to obtain a printed circuit board of FIG. 1(a)." Taniguchi also fails to disclose *each of said films having a thickness of 12.5 μm to 80 μm* . Applicants respectfully direct the Office's attention to lines 47-48 of column 7 of Taniguchi which disclose a film insulator having a thickness of 100 μm . The benefit of the thickness range disclosed in the present application is it avoids a substantial increase in the total thickness of the board and may avoid difficulty in realizing a wiring of high density as described in paragraph [0056] of the present application.

Accordingly, it is respectfully submitted independent claim 1, and claim 2 depending therefrom, are not anticipated by Taniguchi.

II. Rejection Under 35 U.S.C. § 103

Claims 21 and 24 were rejected under 35 U.S.C. § 103 as unpatentable over Taniguchi in view of U.S. Patent Application No. 2002/0134582 to Celaya ("Celaya"). This rejection is respectfully traversed.

Amended claim 21 recites a "multi-layer circuit wiring board comprising a laminate of resin films *and an adhesive layer for bonding said films...*" and "each of said films having a thickness of 12.5 μm to 80 μm ..."

Amended claim 24 recites "...a first adhesive layer for bonding said second film to said first film; and a second adhesive layer for bonding said third film to said first film, each of said first, second and third films having a thickness of 12.5 μm to 80 μm , and each of said adhesive layers having a thickness of 30 μm or less."

Neither Taniguchi nor Celaya, taken individually or in combination, discloses or suggests the above-described recitations of claims 21 and 24. As previously discussed, Taniguchi fails to disclose an adhesive layer for bonding said films or films having a thickness of 12.5 μm to 80 μm .

Celaya discloses a substrate 12, a circuit pattern 71 formed on the top surface 51 of the substrate 12 for connecting to IC 20, and a circuit pattern 72 formed on the bottom surface 52 of the substrate 12 for connecting the substrate 12 to a motherboard 30.

However, the substrate 12 disclosed in Celaya has only a top surface 51 and a bottom surface 52 and therefore is not a multi-layer circuit wiring board comprising a laminate of resin films. Consequently, Celaya fails to disclose an adhesive for bonding said films or films having a thickness of 12.5 μm to 80 μm .

In view of the above Applicants respectfully submit that the rejection is traversed.

III. Conclusion


Consequently, in light of the above discussion and in view of the present amendment, this application is believed to be in condition for allowance and an early and favorable action to that effect is respectfully requested.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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